

E 26161597

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. ..... 09/026,042  
Priority Filing Date ..... February 19, 1998  
Inventor ..... Sujit Sharan et al.  
Assignee ..... Micron Technology, Inc. and Applied Materials, Inc.  
Priority Group Art Unit ..... 1763  
Priority Examiner ..... P. Hassanzadeh, Ph.D.  
Attorney's Docket No. ..... MI22-1902  
TITLE: RF Powered Plasma Enhanced Chemical Vapor Deposition Reactor and  
Methods of Effecting Plasma Enhanced Chemical Vapor Deposition

Assistant Commissioner for Patents  
Washington, D. C. 20231  
Attention: Official Draftsman

SUBSTITUTE DRAWING REQUEST

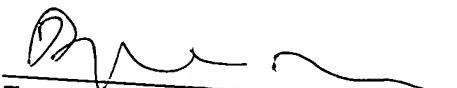
Please enter the enclosed substitute drawings in the above-referenced application  
in place of drawings originally filed. The content of the drawings are identical to those now  
on file in this application.

Acknowledgment of receipt of the formal drawings and their acceptance into the file  
is requested.

Respectfully submitted,

Date: 3-21-02

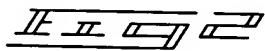
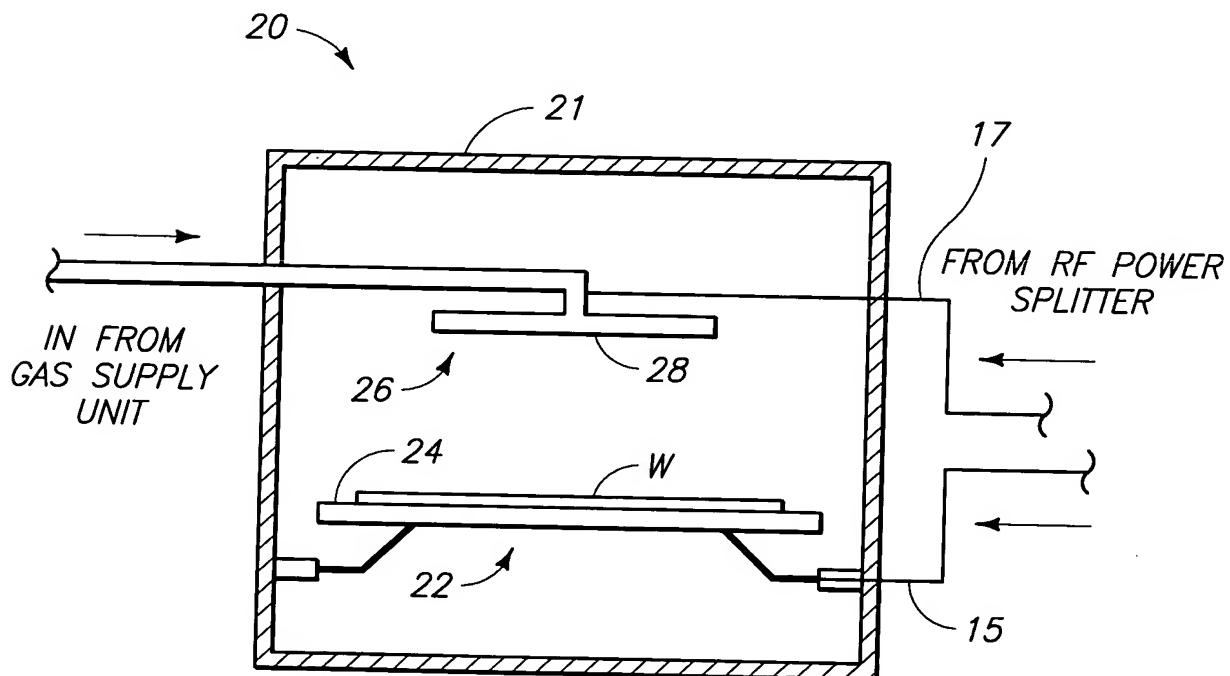
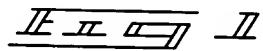
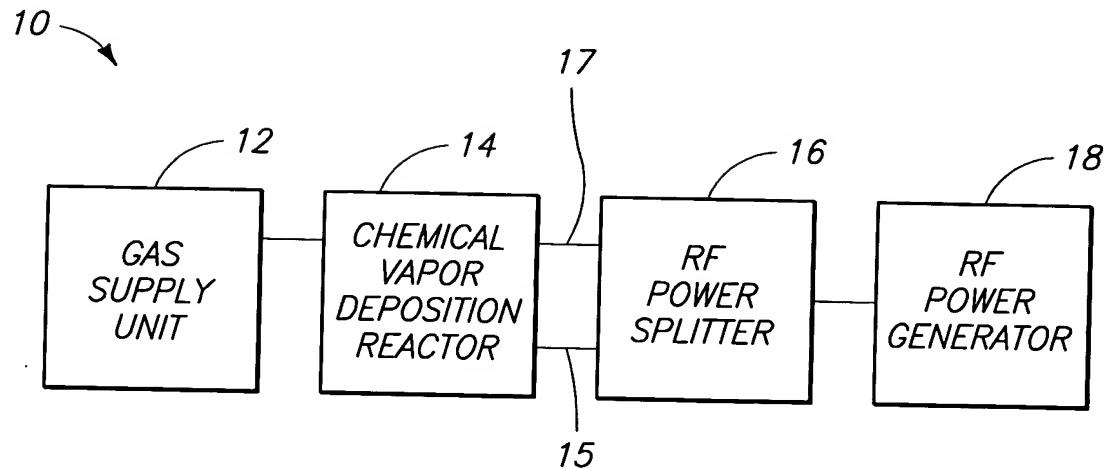
By:

  
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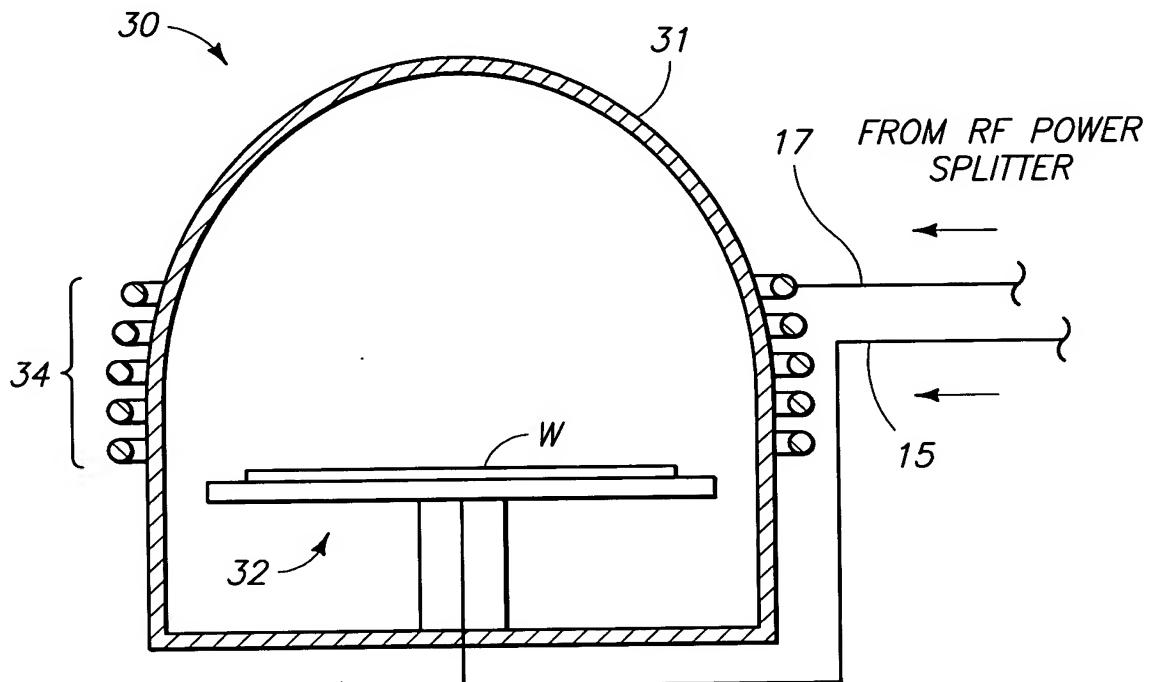
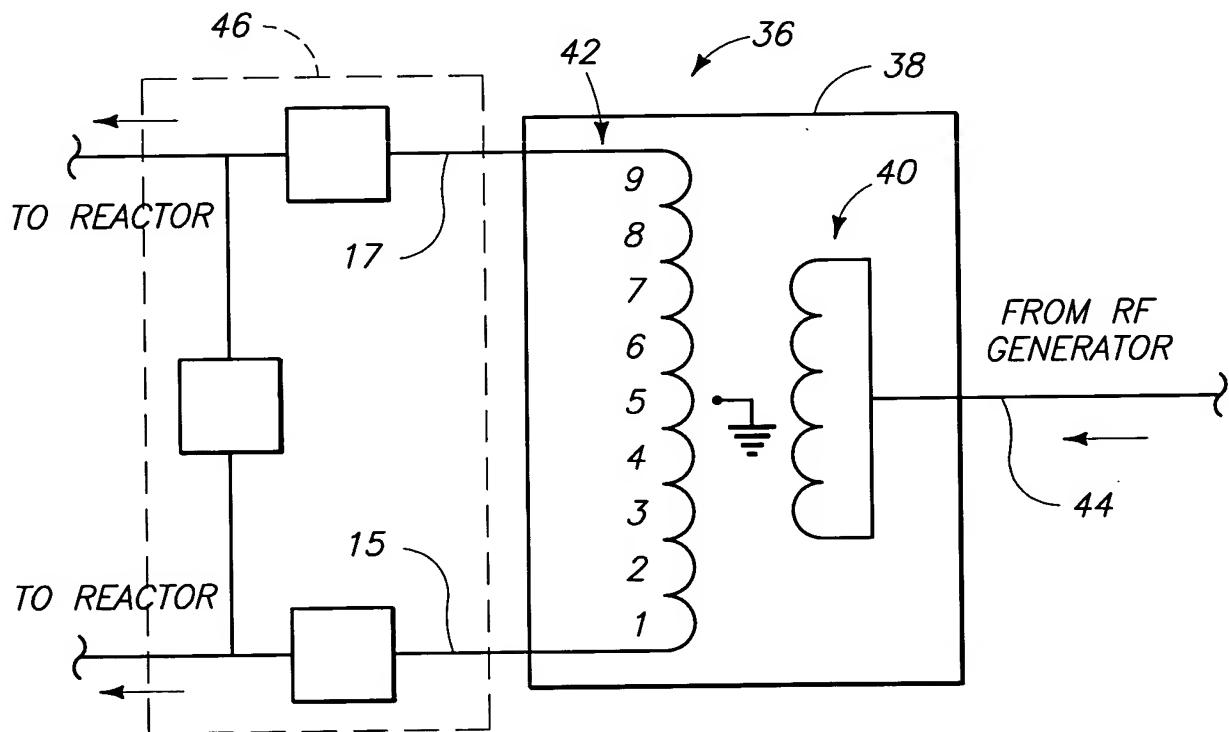
Enclosures: 4 Sheets of Formal Drawings, Figs. 1-6.

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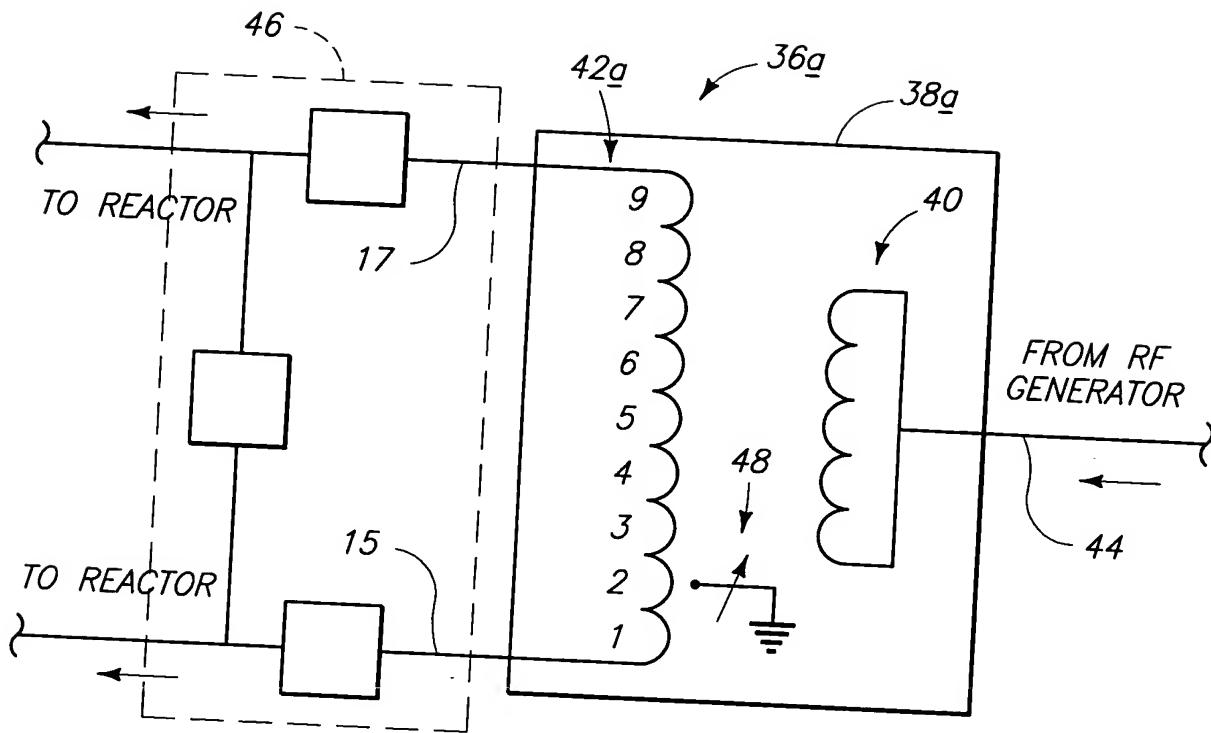
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